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Revision 20231109

LNPTM THERMOTUFTM COMPOUND VC006

VC-1006 REGION AMERICAS

DESCRIPTION

LNP THERMOTUF VC006 compound is based on Super Tough Nylon resin containing 30% carbon fiber. Added features of this grade include: Impact Modified, Electrically Conductive.

TYPICAL PROPERTY VALUES

PROPERTIES UNITS **TEST METHODS** TYPICAL VALUES MECHANICAL⁽¹⁾ Tensile Stress, yld, Type I, 5 mm/min 197 MPa ASTM D638 197 Tensile Stress, brk, Type I, 5 mm/min MPa ASTM D638 Tensile Strain, yld, Type I, 5 mm/min 2.9 % ASTM D638 Tensile Strain, brk, Type I, 5 mm/min 2.9 % ASTM D638 Tensile Modulus, 50 mm/min 20700 MPa ASTM D638 Flexural Stress, yld, 1.3 mm/min, 50 mm span 293 MPa ASTM D790 Flexural Stress, brk, 1.3 mm/min, 50 mm span ASTM D790 286 MPa Flexural Modulus, 1.3 mm/min, 50 mm span 15300 ASTM D790 MPa Tensile Stress, yield, 5 mm/min 193 MPa ISO 527 ISO 527 Tensile Stress, break, 5 mm/min 193 MPa ISO 527 Tensile Strain, yield, 5 mm/min 2.9 % Tensile Strain, break, 5 mm/min 2.9 % ISO 527 Tensile Modulus, 1 mm/min 19340 MPa ISO 527 **Flexural Stress** 284 MPa ISO 178 Flexural Modulus, 2 mm/min 15530 MPa ISO 178 IMPACT (1) Izod Impact, unnotched, 23°C 1070 J/m ASTM D4812 207 ASTM D256 Izod Impact, notched, 23°C J/m Multiaxial Impact 7 ISO 6603 Instrumented Dart Impact Total Energy, 23°C 32 ASTM D3763 Izod Impact, unnotched 80*10*4 +23°C 74 kJ/m² ISO 180/1U Izod Impact, notched 80*10*4 +23°C 20 kJ/m² ISO 180/1A THERMAL (1) HDT, 0.45 MPa, 3.2 mm, unannealed 261 °C ASTM D648 °C HDT, 1.82 MPa, 3.2mm, unannealed 250 ASTM D648 1/°C CTE, -30°C to 30°C, flow 3.4E-05 ASTM D696 CTE, -30°C to 30°C, xflow 1.02E-04 1/°C ASTM D696 HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm 258 °C ISO 75/Bf HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm 240 °C ISO 75/Af PHYSICAL (1) Specific Gravity 1.21 ASTM D792 Density 1.21 g/cm³ ASTM D792 Moisture Absorption, (23°C/50% RH/24 hrs) 0.62 % ASTM D570

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CHEMISTRY THAT MATTERS



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.25	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1	%	ASTM D955
Moisture Absorption (23°C / 50% RH)	0.95	%	ISO 62
INJECTION MOLDING ⁽³⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.15	%	
Melt Temperature	280 – 295	°C	
Front - Zone 3 Temperature	295 – 305	°C	
Middle - Zone 2 Temperature	275 – 290	°C	
Rear - Zone 1 Temperature	260 – 270	°C	
Mold Temperature	95 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 - 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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